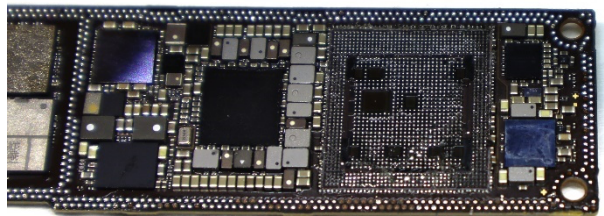


The exhibit CPU was then carefully removed from the damaged logic board using heat (Picture Ref 6.2.9 & 6.2.10). The CPU looked in good condition with no visible damage observed. The CPU has a covering of black underfill which required careful removal.

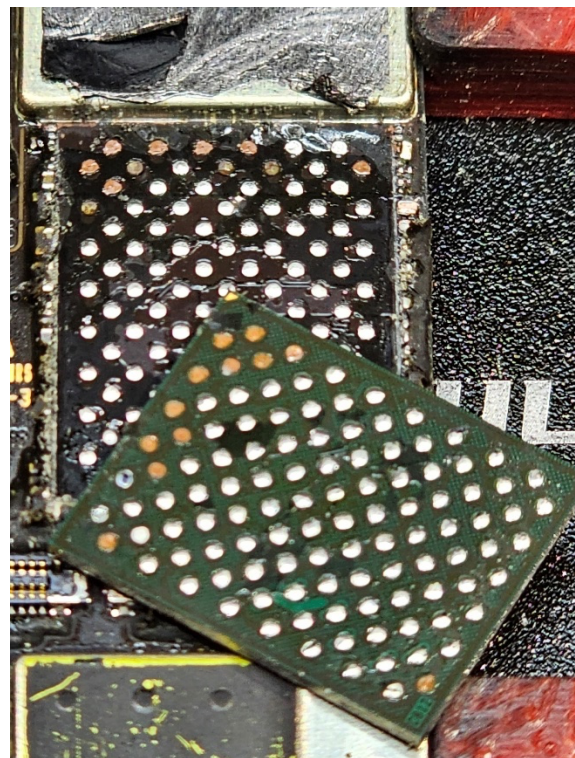


Picture Ref 6.2.9: IMG_5855.JPG



Picture Ref 6.2.10: IMG_5856.JPG

The exhibit NAND was then carefully removed from the damaged logic board using heat (Picture Ref 6.2.11 & 6.2.12). Unfortunately, unlike the CPU it was immediately clear the NAND had been partially disconnected from the logic board due to the bend in the board (Picture Ref 6.2.13) resulting in several pads being ripped from the NAND itself.



Picture Ref 6.2.11: NAND Removed.JPG